ABSTRACT

WAFER POSITION CALIBRATION METHOD AND APPARATUS, READABLE STORAGE MEDIUM AND DEVICE

The present invention discloses a wafer position calibration method and apparatus, a readable storage medium and a device. The wafer position calibration method includes the following steps: scanning an object to be manipulated to identify an alignment mark on the object to be manipulated, so as to obtain two actual positions of the alignment mark; based on the two actual positions, determining a righting angle for the object to be manipulated; and based on the righting angle, controlling the object to be manipulated to rotate. With adoption of the calibration method, that current manual placement or pre-aligning by a robotic arm cannot meet high-precision requirement can be solved, the angle error of the object to be manipulated is reduced, and therefore the precision of subsequent test of the object to be manipulated is improved.

FIG. 1